

IN THE CLAIMS:

Claims 3-5, 8 and 9 were previously cancelled. Claim 6 has been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Previously presented) A semiconductor assembly comprising:
a substrate having a surface;
a semiconductor die having a plurality of edges, having an active surface having a plurality of bond pads thereon located adjacent at least two edges of the plurality of edges, and having a back side surface, the semiconductor die having at least a portion of the back side surface adhesively attached to at least a portion of the surface of the substrate;
a gel elastomer contacting at least a portion of the active surface of the semiconductor die;
a layer of adhesive substantially covering a surface of the gel elastomer;
a heat sink attached to the gel elastomer by the layer of adhesive; and
an encapsulation material covering a portion of the surface of the substrate, the plurality of edges of the semiconductor die, and at least one bond pad of the plurality of bond pads located adjacent at least two edges of the semiconductor die, wherein the encapsulation material excludes covering the heat sink.
2. (Original) The semiconductor assembly of claim 1, wherein the heat sink includes a plurality of fins thereon.

3.-5. (Cancelled)

6. (Currently amended) A semiconductor assembly comprising:
a substrate having a plurality of electrical connections on a portion of a surface thereof;
at least one semiconductor die having a plurality of bond pads on a first portion of an active surface thereof and having a back side surface, a portion of the back side surface adhesively attached to a portion of the surface of the substrate;
a plurality of wire bonds connecting at least a portion of the plurality of bond pads of the at least one semiconductor die to at least a portion of the plurality of electrical connections of the substrate, a gel elastomer contacting a second portion of the active surface of the at least one semiconductor die;
a layer of adhesive substantially covering a surface of the gel-elastomer;
a heat sink attached to the gel elastomer by the layer of adhesive; and
an encapsulant material covering a portion of the surface of the substrate, the plurality of bond pads on the active surface of the at least one semiconductor die, a portion of the active surface of the at least one semiconductor die, and the plurality of wire bonds, wherein the encapsulation material excludes covering the heat sink.

7. (Original) The semiconductor assembly of claim 6, wherein the heat sink includes a plurality of fins thereon.

8. (Cancelled)

9. (Cancelled)